CLAIMS

1. An electronic device unit comprising:

a heat sink including:

a base plate;

a protrusion protruding from the base plate in a first direction intersecting the base plate, the protrusion being thermally connectable to a first heating element mounted on a first substrate;

a plurality of first fins protruding from the base plate in an opposite direction to the first direction, the plurality of first fins being aligned in a second direction intersecting the first direction;

a first boss protruding from the base plate more than the plurality of first fins in the opposite direction to the first direction, the first boss allowing a fastener to be attached to the first boss, the fastener serving to couple an outer wall of a housing and the base plate; and

a second boss protruding from the base plate in the first direction, the second boss allowing a fastener to be attached to the second boss, the fastener serving to couple the first substrate and the base plate;

a first substrate on which a first heating element is mounted in a state where the first heating element is thermally connected to the protrusion of the heat sink;

an attachment base being placed on a side opposite to the heat sink in the first direction from the first substrate;

a second substrate being placed in the first direction from the attachment base; and

a storage holder being placed in the first direction from the second substrate to hold an auxiliary storage device, wherein

the electronic device unit is configured to be attachable to a housing in a state where the heat sink, the first substrate, the attachment base, the second substrate, and the storage holder are integrated with one another, and

the attachment base includes

a middle wall being placed between the first substrate and the second substrate,

a first stud protruding from the middle wall in the opposite direction to the first direction, the first stud allowing a fastener to be attached to the first stud, the fastener serving to couple the first substrate and the attachment base, and

a second stud protruding from the middle wall in the first direction, the second stud allowing a fastener to be attached to the second stud, the fastener serving to couple the second substrate and the attachment base.

2. The electronic device unit according to claim 1, wherein

the protrusion includes a concavity being concave in the first direction from a first surface on a side opposite to the first heating element, and

part of the plurality of first fins protrudes from a bottom portion of the concavity in the opposite direction to the first direction.

3. The electronic device unit according to claim 1 or 2, further comprising a plurality of second fins protruding from the base plate in the first direction, the plurality of second fins being aligned in the second direction.

4. The electronic device unit according to claim 1, further comprising a second heating element being mounted on the first substrate or the second substrate, the second heating element being provided in a state where the second heating element is thermally connected to the attachment base through a heat conducting member,

wherein the heat conducting member includes

a grease being applied on the attachment base, and

a sheet being interposed between the grease and the second heating element.

5. The electronic device unit according to claim 4, wherein the storage holder includes a heat insulating wall covering at least a second surface of the auxiliary storage device, the second surface being located in the opposite direction to the first direction.